



LONGHILL INDUSTRIES LTD.

MODEL LH8320

SEMI-AUTO CONTACTLESS WAFER MOUNTER

FEATURES

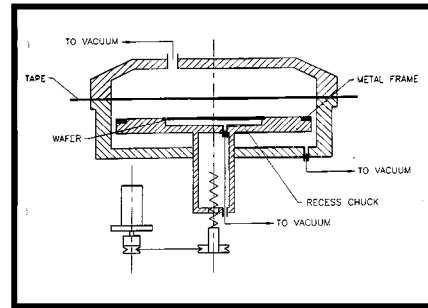
- Air bubble free mounting
- Minimal contact with wafer
- Vacuum mount, no roller
- 8" and 12" wafer capability
- Partial wafer mounting
- PC control
- Fully programmable mounting parameters



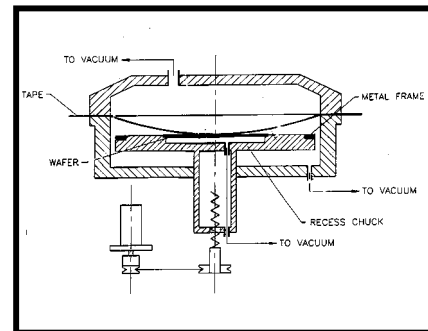


FEATURES :

1. Contactless mounting
Recessed chuck holds wafer at edge only.
Tape mounted by vacuum method. No roller required.
No air bubble.
2. Chuck configuration independent of wafer thickness.
3. Uniform tape mounting pressure across entire surface of wafer.
Micro cracks due to localised pressure are avoided.
4. Controlled tape tension.
5. Auto tape feed and cut. Auto used tape rewind system and separator tape rewind system also available.
6. Wafer can be mounted at 0°, 90°, 180° and 270° relative to film frame by rotating chuck.
7. Proportional pneumatic valves, closed loop pressure control system with fully programmable mounting parameters.
8. Easy conversion.
Wafer size change less than 1 minute
Wafer, frame and tape change less than 8 minutes.
9. Partial wafer mounting possible.
10. PC control with menu programming. Monitor display of number of wafers processed.
11. Diagnostic program with display to indicate error location.
12. Safety light beam curtain and EMO.
13. Film frame and wafer presence detection.
14. End of tape detection.
15. Dual ionizers to eliminate static charge.
16. Machine status lamp & stand-alone construction.
Built-in vacuum pump to ensure stable vacuum.
17. UV tape capability.
18. UL / SEMI S2-93 safety standard compatible.



Chamber closed. Vacuum generated within chamber.



Tape Stretched & Ballooned Down To Touch Wafer Back Side Due To Differential Vacuum, Starting At Center Of Wafer.

SPECIFICATION:	
Wafer Diameter:	8" and 12" (200mm and 300mm)
Frames:	Standard Disco and K&S frames
Tapes: width	410mm for 300mm wafer, 343mm for 200mm wafer
length	100M
thickness	0.05 – 0.15mm
Wafer Table:	Non-contact type with vacuum system
Wafer Table Temperature:	Up to 60° C (optional)
Cycle Time:	60 seconds for 300mm, 40 seconds for 200mm wafer
Through-put:	40 – 60 wafers per hour
Facilities:	Electrical: 220Vac, 50/60Hz, 15A
	Compressed air: 60 psi dry air
Machine Dimension:	900mm(W) x 1320mm(D) x 1700mm(H)
Shipping Dimension:	1100mm(W) x 1520mm(D) x 1900(H)
Machine Weight:	370 Kg estimated
Shipping Weight:	500 Kg estimated